



HSEC8-130-01-L-D-EM2



DEC8-160-01-S

(0,80 mm) .0315"

HSEC8-EM, DEC8 SERIES

EDGE MOUNT EDGE RATE™ CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-EM

Insulator Material: Liquid Crystal Polymer
Contact: BeCu
Plating: Au or Sn over 50µ" (1,27 µm) Ni
Operating Temp: -55°C to +125°C
Card Insertion Depth: (3,15 mm) .125" nominal
Lead-Free Solderable: Yes
RoHS Compliant: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Other platings
- Contact Samtec.

Note: While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.

Note: Requires PCB thickness of (1,60 mm) .062" ±(0,08 mm) .003"

HSEC8

1

POSITIONS PER ROW

01

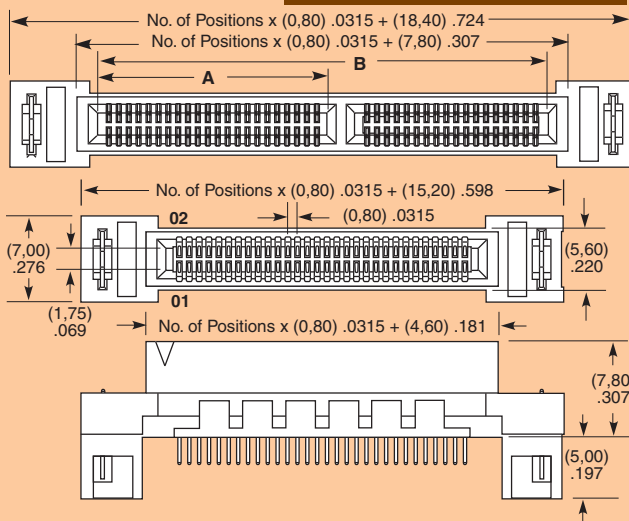
PLATING OPTION

D

EM2

Mates with:
 (1,60 mm) .062" thick cards, ECDP, HSC8

10, 20, 30, 40, 50, 60



-L
 = 10µ" (0,25 µm)
 Gold on contact, Matte Tin on tail

-S
 = 30µ" (0,76 µm)
 Gold on contact, Matte Tin on tail

POS. PER ROW	A	B
40	(18,90) .744	(36,60) 1.441
50	(22,90) .902	(44,60) 1.756
60	(26,90) 1.059	(52,60) 2.071

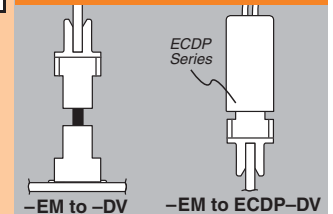
-EM2
 = (1,60 mm) .062" thick PCB

OTHER SOLUTIONS

Polarized mates for ECDP Series twinax cables

CONNECTOR	CABLE
HSEC8-113	ECDP-08
HSEC8-125	ECDP-16
HSEC8-137	ECDP-24
HSEC8-149	ECDP-32

APPLICATIONS



SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?DEC8

Insulator Material: Black ABS
Contact: BeCu
Plating: Au over 50µ" (1,27 µm) Ni
Operating Temp: -55°C to +125°C
RoHS Compliant: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Other platings
- Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

DEC8

1

POSITIONS PER ROW

LEAD STYLE

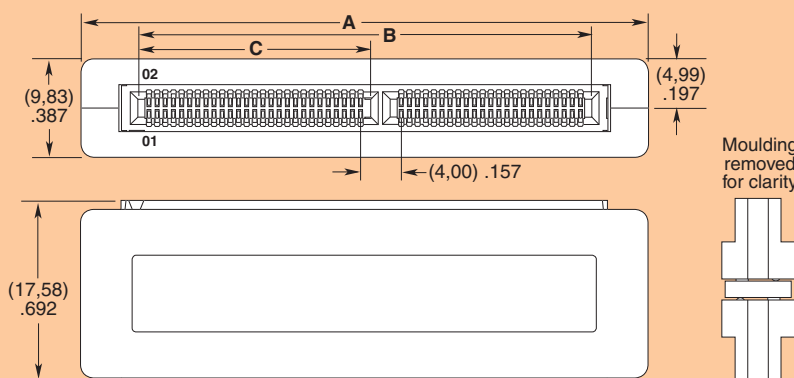
PLATING

Mates with:
 (1,60 mm) .062" thick cards, HSC8

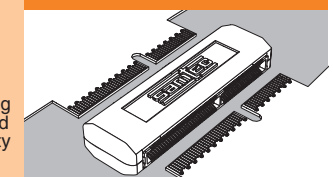
40, 50, 60

-01
 = (1,60 mm) .062" Card Thickness

-S
 = 30µ" (0,76 µm)
 Gold on contact



APPLICATIONS



POSITIONS PER ROW	A	B	C
40	(47,75) 1.880	(36,60) 1.441	(18,90) .744
50	(55,75) 2.195	(44,60) 1.756	(22,91) .902
60	(63,75) 2.510	(52,60) 2.071	(26,90) 1.059

Due to technical progress, all designs, specifications and components are subject to change without notice.

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